



PERSISTENT MEMORY PMM SUMMIT

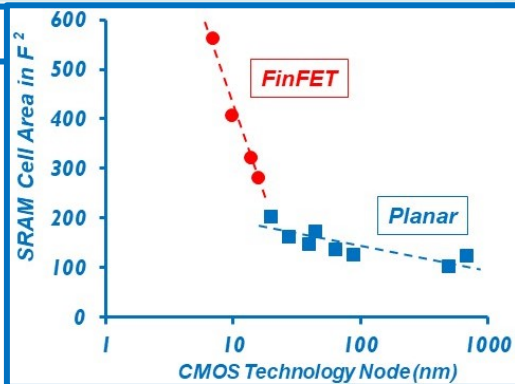
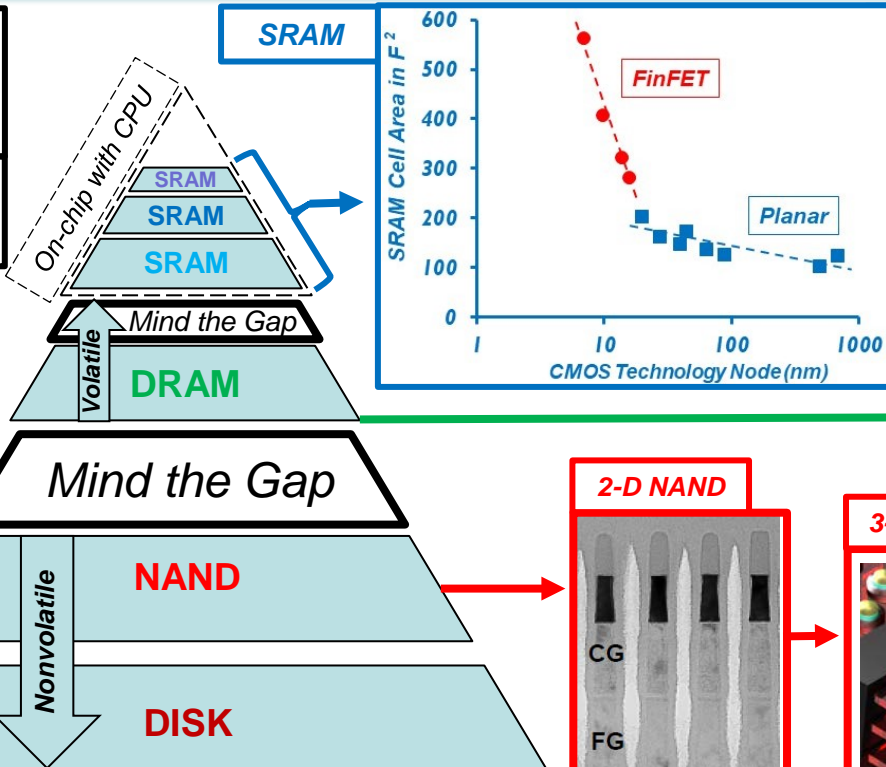
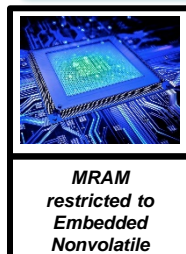
JANUARY 24, 2018 | SAN JOSE, CA

Unleashing MRAM as Persistent Memory

Andrew J. Walker PhD
Spin Transfer Technologies

- The Creaking Pyramid
 - ◆ Challenges with the Memory Hierarchy
- What and Where is MRAM ?
- State of the Art pMTJ
- Unleashing MRAM
- MRAM Unbound

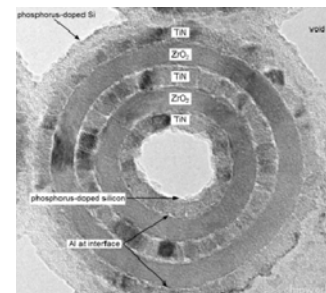
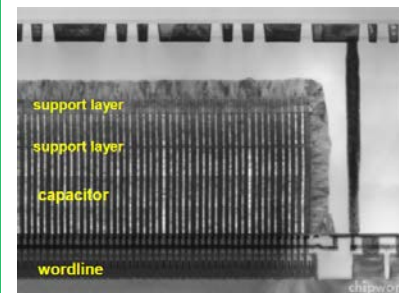
The Creaking Pyramid



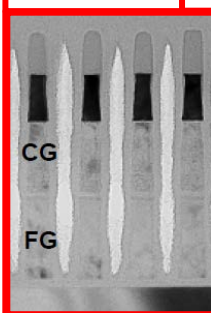
How to deal with leakage, size and inefficient scaling ?

DRAM

What happens after ~30nm pitch ?

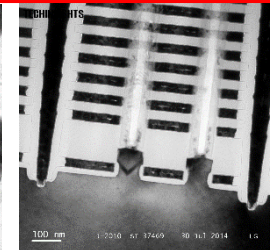
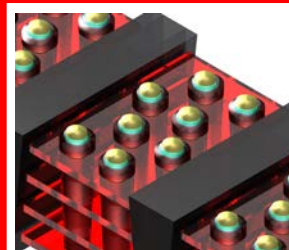


2-D NAND



3-D NAND

How tall can this go ? What is the real cost/bit ?



Challenges within the Memory Hierarchy

◆ SRAM

- ◆ Ever larger cache capacities needed
- ◆ Inefficient scaling in FinFET CMOS
- ◆ Large leakage currents dominating power dissipation

◆ DRAM

- ◆ Scalability reaching fundamental limits close to 30 nm pitch
- ◆ Refresh power dissipation only getting worse
- ◆ Not monolithically 3-D stackable

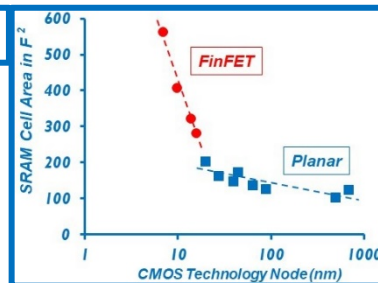
◆ NAND

- ◆ 3-D transition made but how tall can it go ?
- ◆ Can it be laterally shrunk ?
- ◆ What is the real cost per bit?

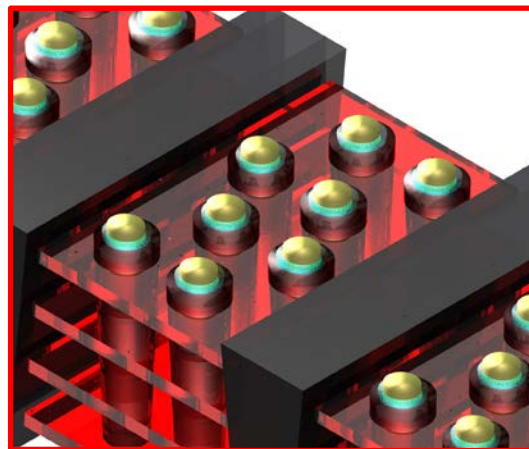
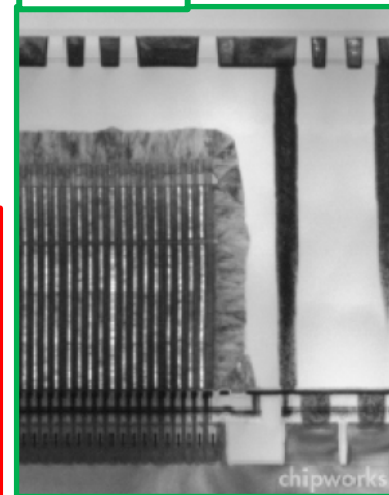
◆ The Gaps

- ◆ Does 3D XPoint™ fit the bill ?
- ◆ Can ReRAM really be made to work ?
- ◆ What else can fill The Gaps ?

SRAM



DRAM



3-D NAND

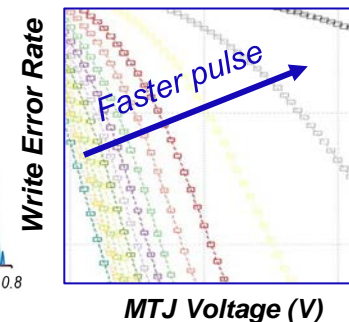
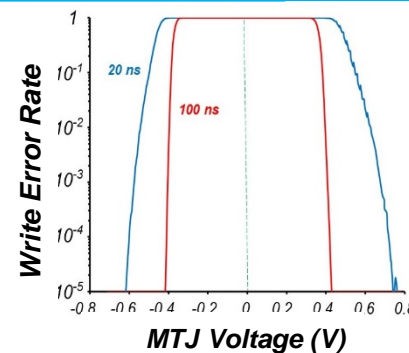
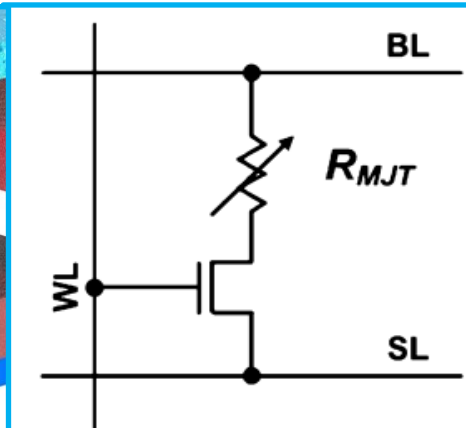
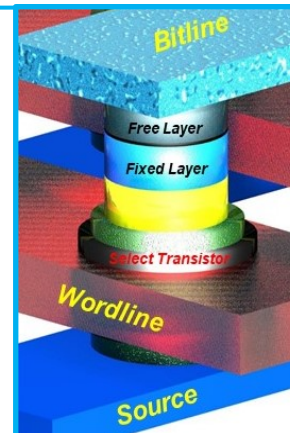
References: S.H. Kang et al., IEDM17., D. James, ASMC 2013

3D XPoint is an Intel/Micron Trademark

What is MRAM ?

◆ Spin-Transfer Torque Magnetic RAM

- ◆ A magnetic ReRAM using a perpendicular Magnetic Tunnel Junction (pMTJ)
- ◆ Writing: flip \underline{M}_{free} vector using electron spin to be parallel or anti-parallel with \underline{M}_{fixed}
- ◆ Writing is **stochastic** – highly unusual for solid-state memory with mathematical description
- ◆ Reading: monitor current through MTJ
 - \underline{M}_{fixed} and \underline{M}_{free} parallel gives low resistance
 - \underline{M}_{fixed} and \underline{M}_{free} anti-parallel gives higher resistance
- ◆ Physics: the relative directions of \underline{M}_{fixed} and \underline{M}_{free} alter the Quantum Mechanical tunneling transmission probability through a thin MgO layer resulting in a resistance change

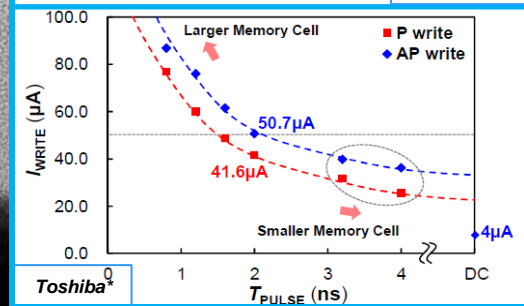
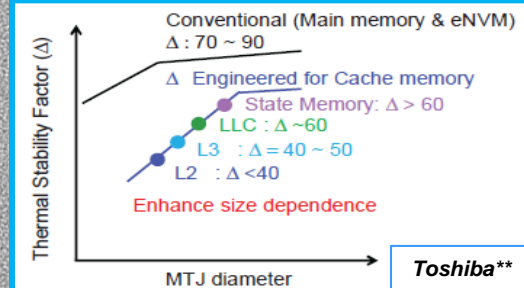
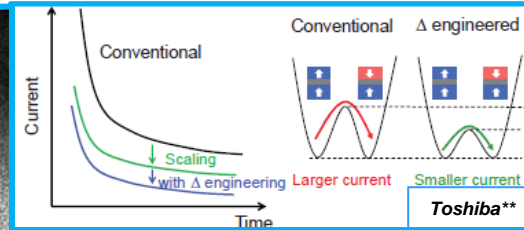
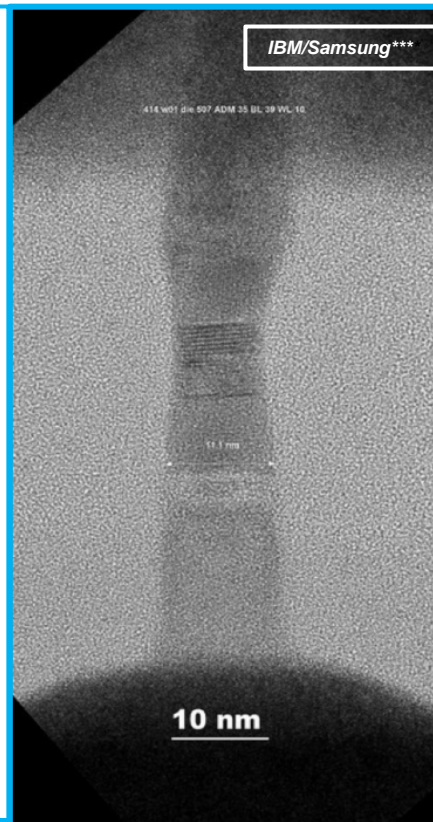


Where is MRAM ?

- Emerging as the embedded NV memory of choice in advanced CMOS
 - ◆ Lower voltage and fewer masks than traditional Flash
- But.... Stochastic behavior limiting MRAM to embedded NV
 - ◆ Low Write Error Rates need high switching current and long write pulses which cause MgO wearout which limits endurance
- And...Retention and endurance are strongly inversely linked
 - ◆ NV retention needs stiff M_{free} which needs high switching current which causes MgO wearout which limits endurance
- Is MRAM confined to the embedded NV “cage” ?

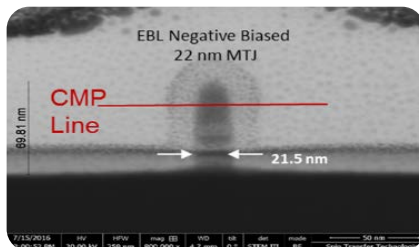
State of the Art pMTJ

- Retention – Endurance – Switching Current engineering through:
 - Scaling
 - Magnetic materials engineering
- Scaled soft magnetic pMTJ allows:
 - Lower switching current
 - Lower write power dissipation
 - High endurance
 - Smaller bitcells
 - Some level of persistence
- “Conservation of Misery”
 - Are R_{low} and R_{high} sufficiently separated ?
 - Manufacturing control and distributions
- Are SRAM/DRAM really replaceable ?
- Are The Gaps Fillable ?
- What can be done to help unleash MRAM?**



Unleash MRAM with Spin Transfer Technologies

Unique Facility



Smaller pMTJ

10ns R/W times

Sub-20nm pillars

Gb Densities

Advanced process
nodes

Partnered w/TEL

Unique Magnetics



Patented pMTJ Enhancement

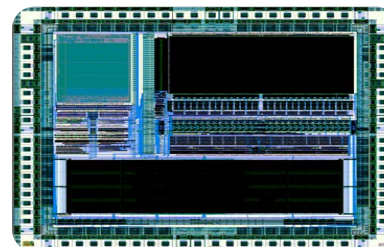
Faster Switching

Lowers R/W current

Critical for smaller
geometries

Heavily Patented

Unique Circuits



Endurance Engine

Increases Endurance
by up to six orders

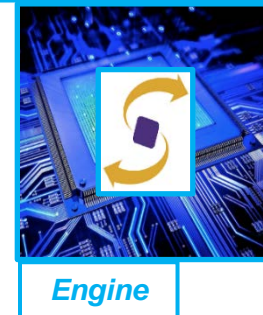
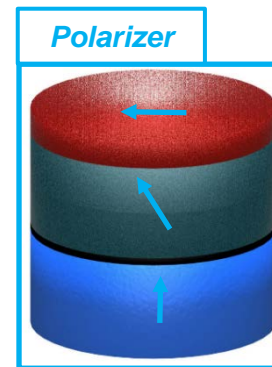
Eliminates R/W Errors

Shortens time to high
yield.

Unleash MRAM with Spin Transfer Technologies

STT's **Engine** – The “SanDisk of MRAM” and The Benefit of Synergy

- Significantly reduces the switching current requirements
- Enhances speed to 10ns
- Boosts endurance by 5 to 6 orders of magnitude with no retention change
- Allows unique embedded NV and SRAM-like capabilities
- Tuned to anyone's MRAM
- Purely circuit-based with no materials or process changes
- No user-visible errors



STT's **Polarizer**

- Significantly reduces switching current requirements
- Increased switching efficiency
- Enhances free layer switching speed
- Enhances read disturb stability



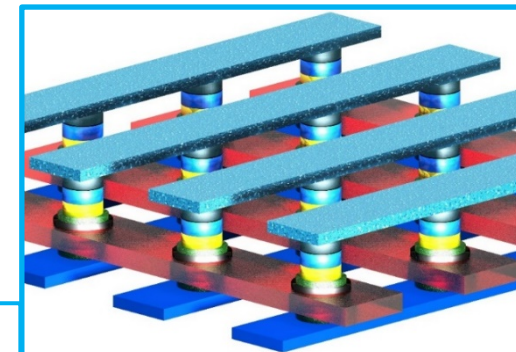
Magnetics

STT's **Magnetics**

- Local highly flexible/fast MRAM fab – capable of 1x/2x nm pMTJs
- BEOL MTJ integration

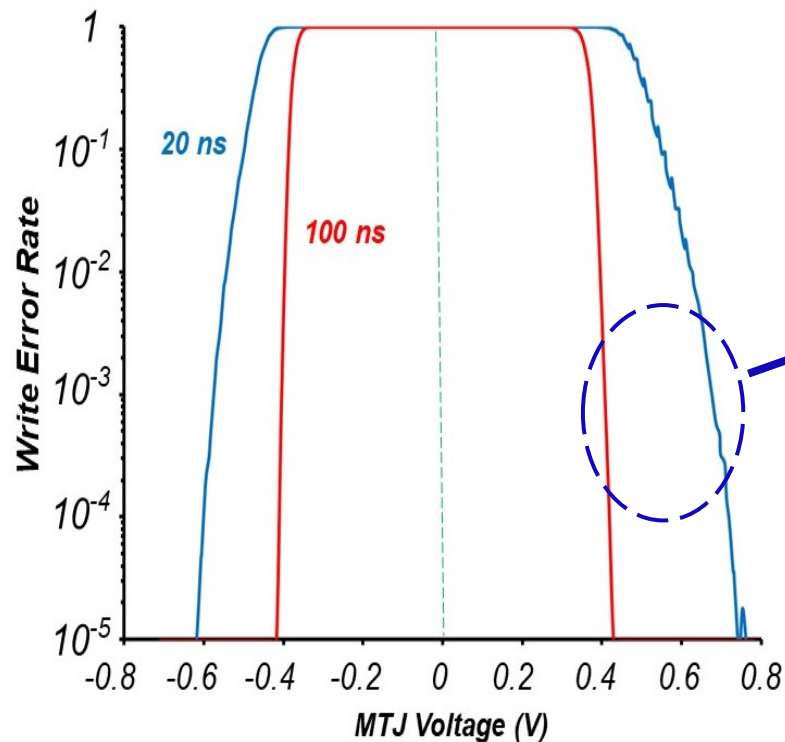
STT's **High Density Persistent Memory and Magnetic DRAM**

- *Selector devices/processes*
- *High density magnetics*

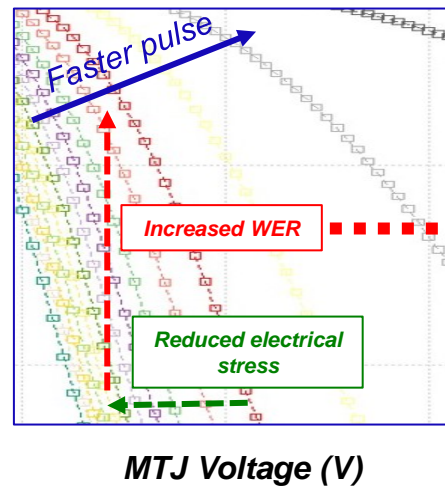


High Density

The Physics of The Engine



Log(Write Error Rate)

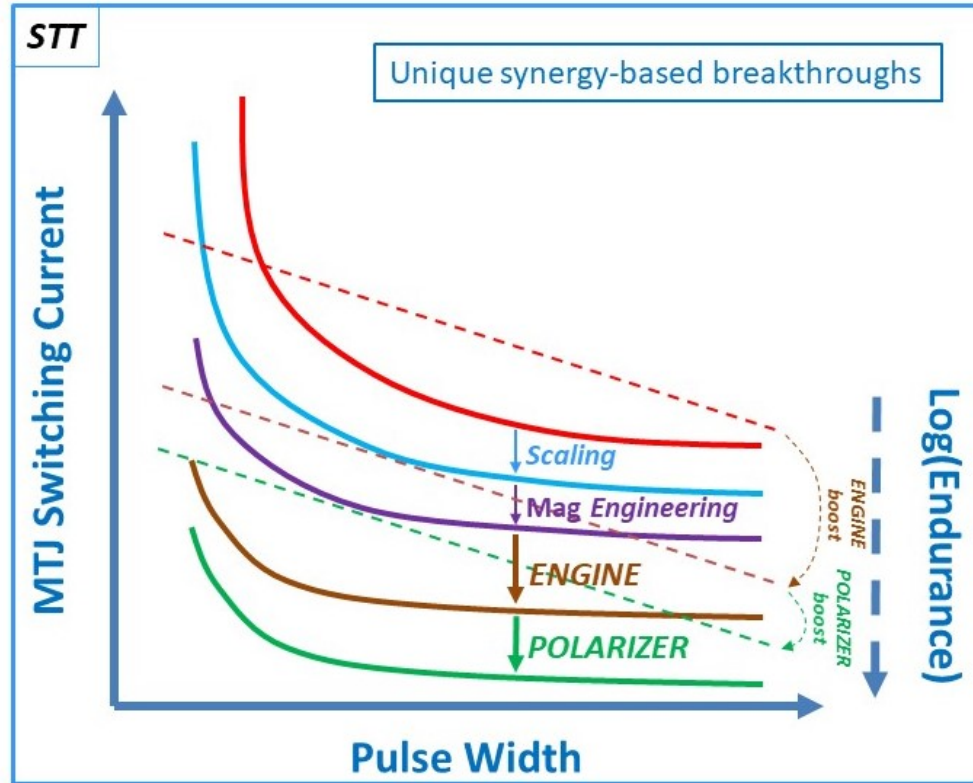


ENGINE



- Engine allows **reduced electrical stress**
 - Results in large endurance increase (5 – 6 orders)
- Engine deals with resultant **WER increase**
 - Managed transparently to the user
 - No change in latency
 - Allows for faster pulses at high endurance

Unleash MRAM with Spin Transfer Technologies

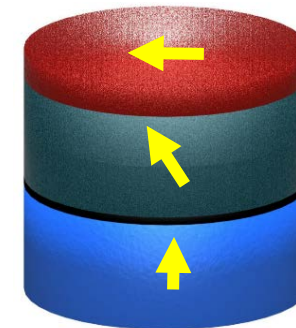


ENGINE



*Circuit – based
Solution*

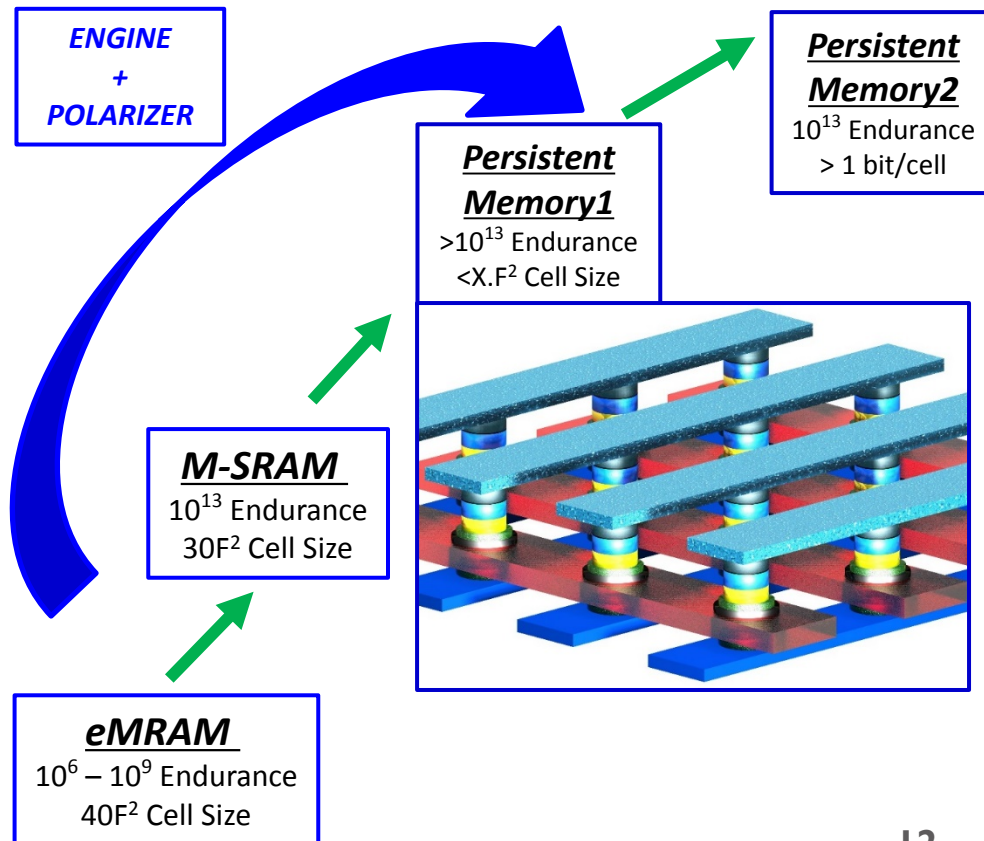
POLARIZER



*Magnetics – based
Solution*

Unleash MRAM with Spin Transfer Technologies

Requirement	Spin's Advantage
Minimize switching currents <ul style="list-style-type: none"> - Easier to integrate with selector devices - Minimize energy 	<ul style="list-style-type: none"> - The ENGINE (IP) - The POLARIZER (IP) - BEOL MTJ Nanofab - Magnetic materials expertise (IP)
Ultra-small MTJs for aggressive pitches	<ul style="list-style-type: none"> - BEOL MTJ Nanofab - MTJ fabrication expertise (IP)
Selector device underneath MTJ	<ul style="list-style-type: none"> - 3D memory and device expertise (IP) - MRAM integration expertise (IP)
Density boosters	<ul style="list-style-type: none"> - > 1 bit per cell (IP)



MRAM Unbound

